

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

Claims 1-4. (canceled).

5. (original): A porous resin obtained by a process comprising the steps of: removing the solvent from the photosensitive resin composition according to claim 1, to form a state that the dispersible compound is dispersed in the polyamic acid resin; removing the dispersible compound, to make the photosensitive resin composition porous; and curing the photosensitive resin composition.

6. (original): The porous resin according to claim 5, wherein the process further comprises the step of patterning the photosensitive resin composition by exposure and development.

7. (original): The porous resin according to claim 5, which is used as an insulating layer of a circuit board.

8. (original): The porous resin according to claim 5, which is used as an insulating layer of a wireless suspension board.

9. (original): A circuit board comprising an insulating layer comprising the porous resin according to claim 5.

10. (original): The circuit board according to claim 9, which is a wireless suspension board.